



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



HCM1A0703

Automotive grade High current power inductors



Product features

- AEC-Q200 Grade 1 qualified
- High current carrying capacity
- Magnetically shielded, low EMI
- Frequency range up to 1 MHz
- Inductance range from 0.1 μ H to 33 μ H
- Current range from 1.6 A to 36 A
- 7.4 mm x 7.0 mm footprint surface mount package in a 3.0 mm height
- Alloy powder core material
- Moisture Sensitivity Level (MSL): 1
- Halogen free, lead free, RoHS compliant

Applications

- Body electronics
 - Central body control module
 - Vehicle access control system
 - Headlamps, tail lamps and interior lighting
 - Heating ventilation and air conditioning controllers (HVAC)
 - Doors, window lift and seat control
- Advanced driver assistance systems
 - 77 GHz radar system
 - Adaptive cruise control (ACC)
 - Automatic parking control
 - Collision avoidance system/Car black box system
- Infotainment and cluster electronics
 - Active noise cancellation (ANC)
 - Audio subsystem: head unit and trunk amp
 - Digital instrument cluster
 - In-vehicle infotainment (IVI) and navigation
 - Port power/USB HUB for front and rear passengers
- Chassis and safety electronics
 - Airbag control unit
 - Electronic stability control system (ESC)
- Engine and Powertrain Systems
 - Electric pumps, motor control and auxiliaries
 - Powertrain control module (PCU)/Engine Control unit (ECU)
 - Transmission Control Unit (TCU)

Environmental Data

- Storage temperature range (Component): -55 °C to +155 °C
- Operating temperature range: -55 °C to +155 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



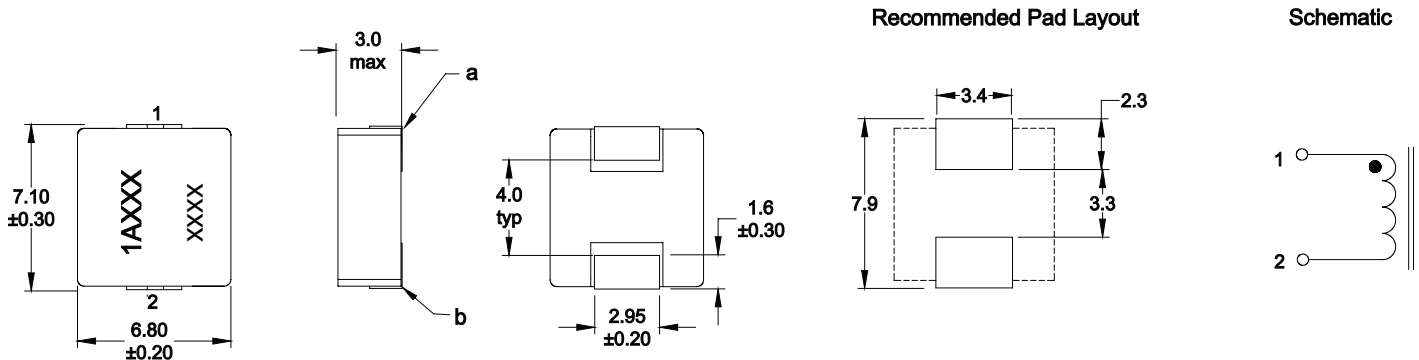
Product Specifications

Part Number ⁶	OCL ¹ (μH) $\pm 20\%$	FLL ² (μH) minimum	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C	K-factor ⁵
HCM1A0703-R10-R	0.10	0.06	22	28	1.2	1.4	2737
HCM1A0703-R15-R	0.15	0.09	18.5	36	1.5	1.8	1358
HCM1A0703-R22-R	0.22	0.13	17	24	2.3	2.7	1386
HCM1A0703-R33-R	0.33	0.21	14	19	3.5	4.0	907
HCM1A0703-R47-R	0.47	0.30	12	17	3.7	4.2	818
HCM1A0703-R56-R	0.56	0.35	10.3	14	4.7	5.2	740
HCM1A0703-R68-R	0.68	0.43	10	15	5.0	5.5	574
HCM1A0703-R82-R	0.82	0.52	8.5	14	6.7	8.0	482
HCM1A0703-1R0-R	1.0	0.64	7.9	13	9.0	10	450
HCM1A0703-1R2-R	1.2	0.76	7.8	11	9.3	10.2	446
HCM1A0703-1R5-R	1.5	1.0	6.6	11	14	15.5	353
HCM1A0703-2R2-R	2.2	1.4	5.7	10	18	20	309
HCM1A0703-3R3-R	3.3	2.1	4.9	9.0	28	30	262
HCM1A0703-4R7-R	4.7	3.0	4.1	8.8	37	40	235
HCM1A0703-6R8-R	6.8	4.3	3.5	6.4	54	60	177
HCM1A0703-8R2-R	8.2	5.2	3.1	5.6	64	68	159
HCM1A0703-100-R	10	6.4	3.0	4.4	71	77.6	153
HCM1A0703-150-R	15	9.6	2.2	4.0	118	127	127
HCM1A0703-220-R	22	14.1	2.0	3.4	135	149	121
HCM1A0703-330-R	33	19.8	1.6	2.3	220	242	81

- Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc, +25 °C
- Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{rms}, I_{rms}, +25 °C
- I_{rms}: DC current for an approximate temperature rise of 30 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155 °C under worst case operating conditions verified in the end application.

- I_{sat}: Peak current for approximately 20% rolloff @ +25 °C
- K-factor: Used to determine B_{pp} for core loss (see graph). B_{p-p} = K * L * ΔI . B_{pp}: (Gauss), K: (K-factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in Amps).
- Part Number Definition: HCM1A0703-xxx-R
HCM1A0703 = Product code and size
xxx= inductance value in μH , R= decimal point,
If no R is present then last character equals number of zeros
-R suffix = RoHS compliant

Dimensions (mm)

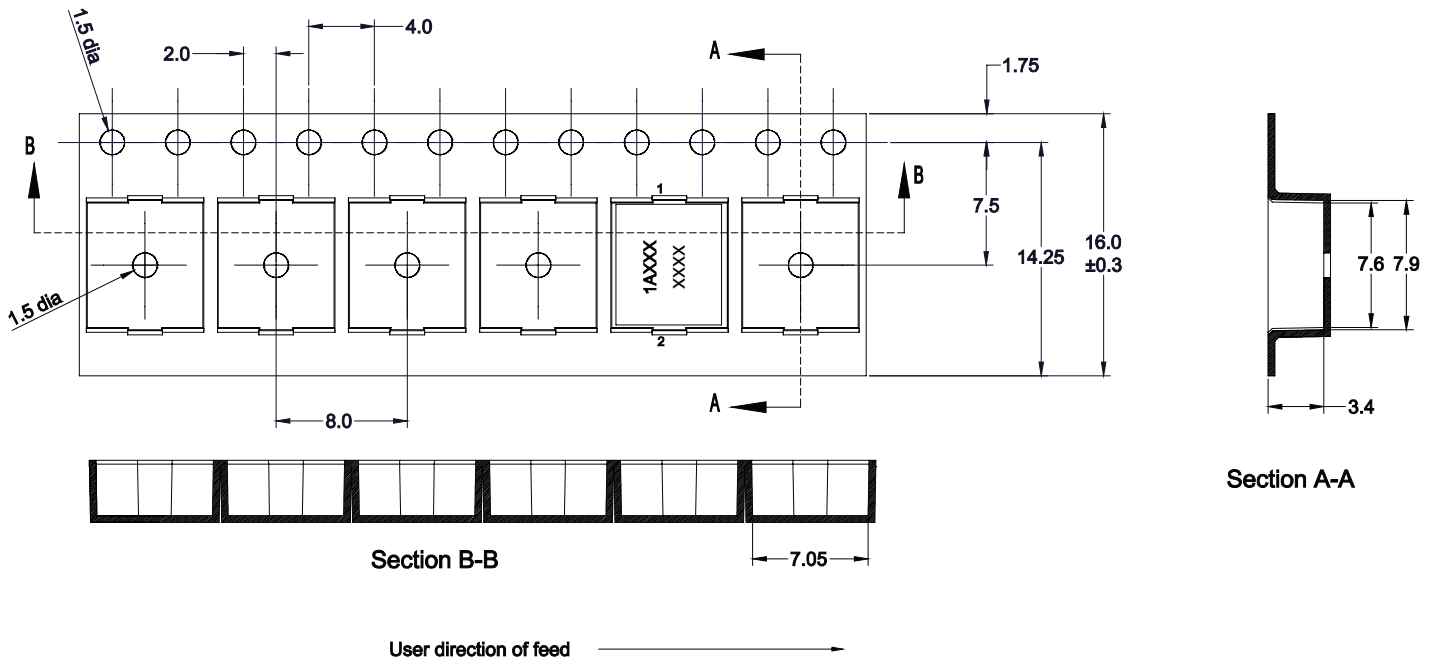


Part marking: 1AXXX=automotive grade, XXX=inductance value in μH , R=decimal point. If no R is present then last character equals number of zeros. xxxx= Lot code
All soldering surfaces to be coplanar within 0.1 millimeters
Tolerances are ± 0.3 millimeters unless stated otherwise
DCR measured from point "a" to point "b"
Color: Grey
Do not route traces or vias underneath the inductor

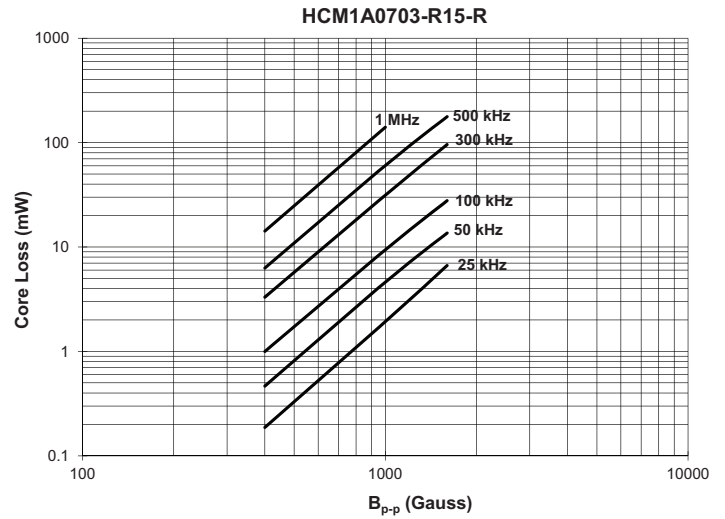
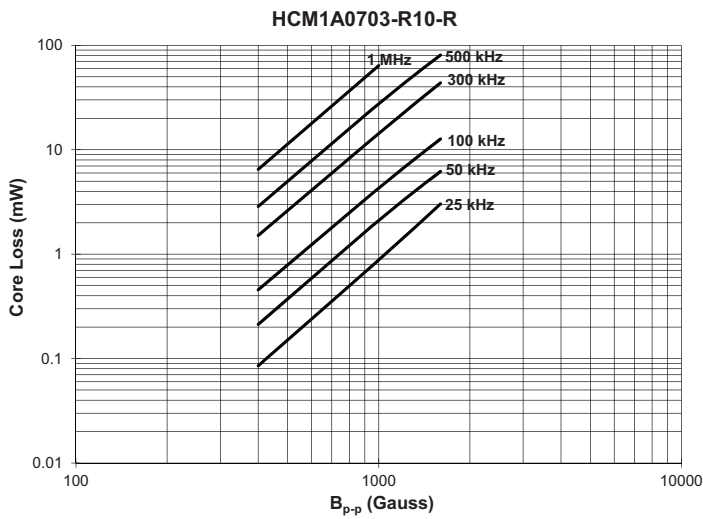
Packaging information (mm)

Drawing not to scale

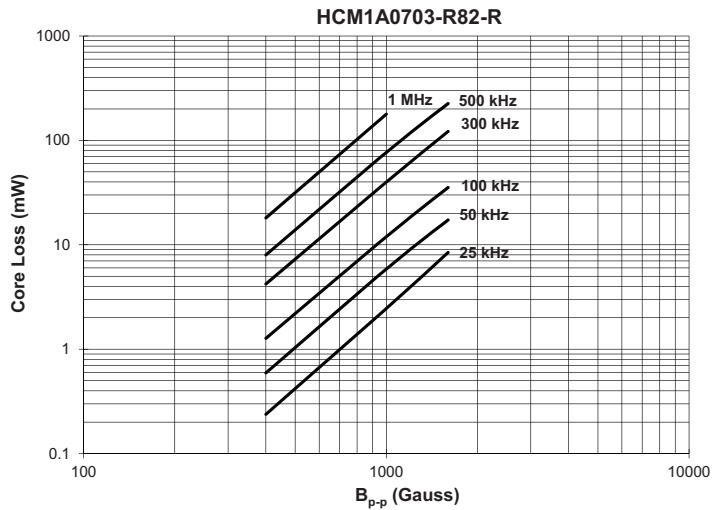
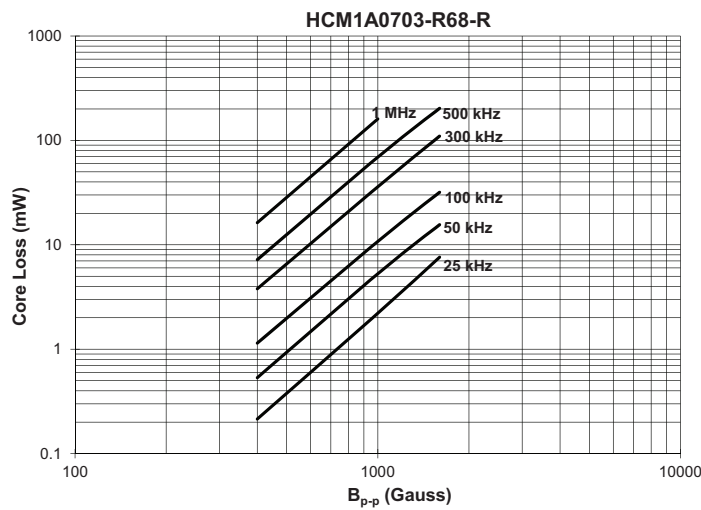
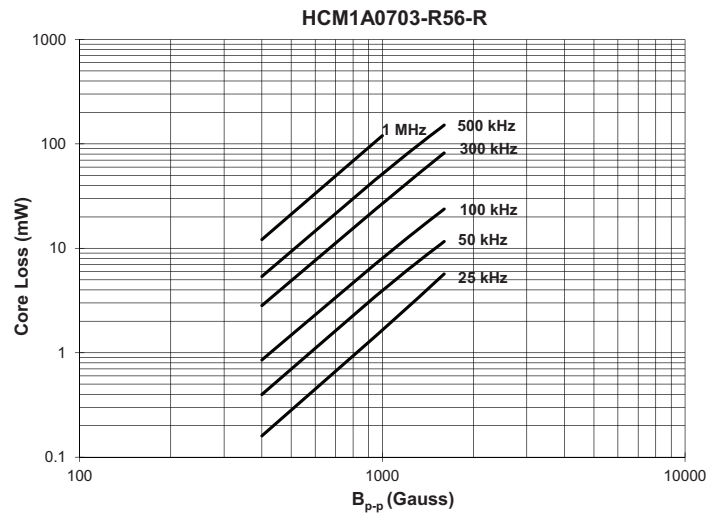
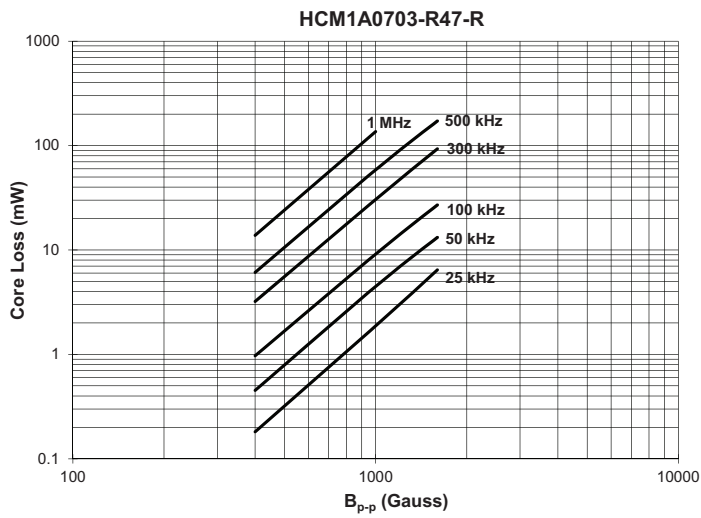
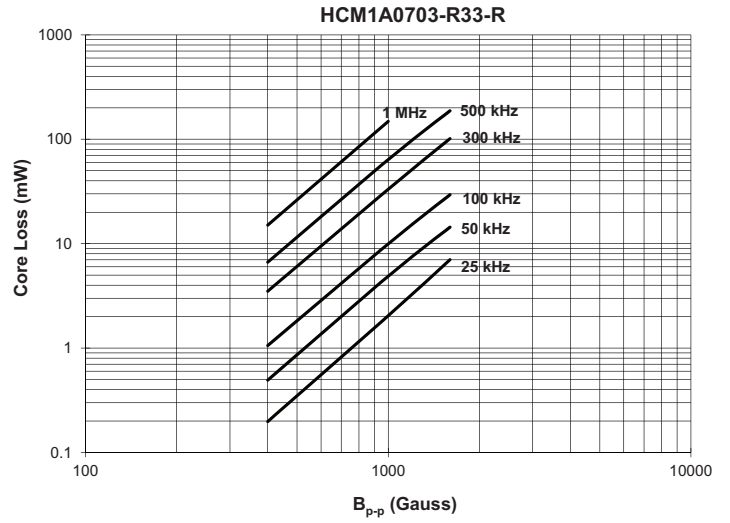
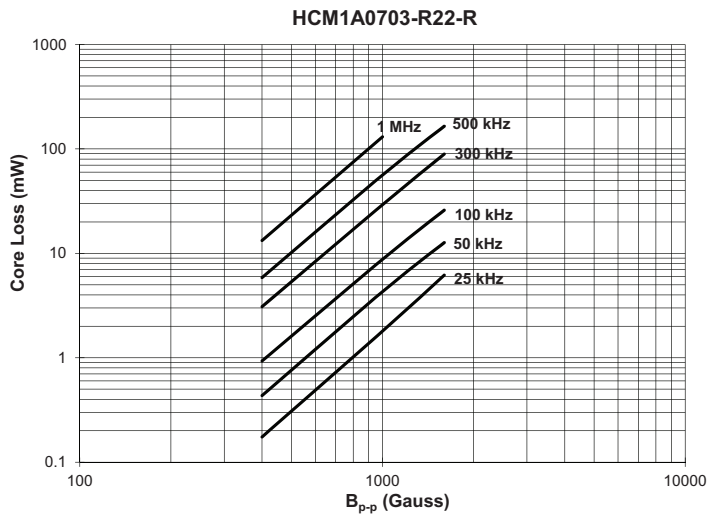
Supplied in tape and reel packaging, 2,000 parts per 13" diameter reel



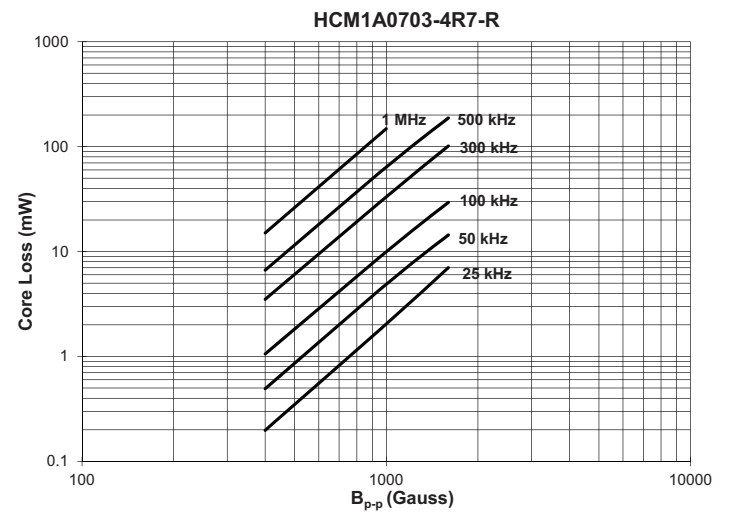
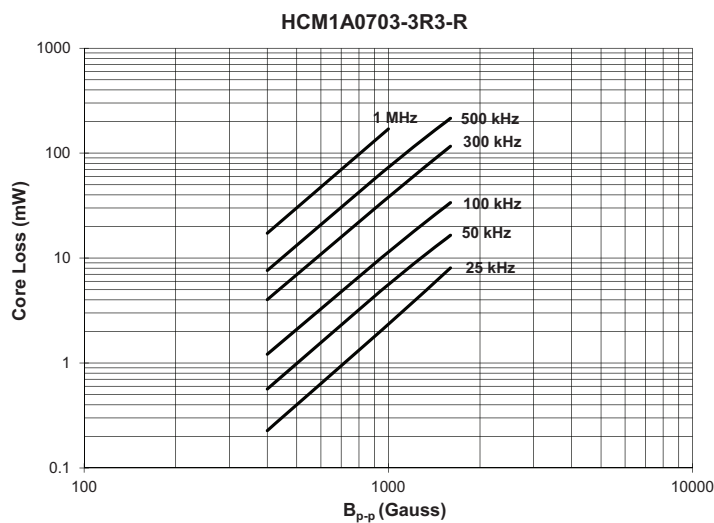
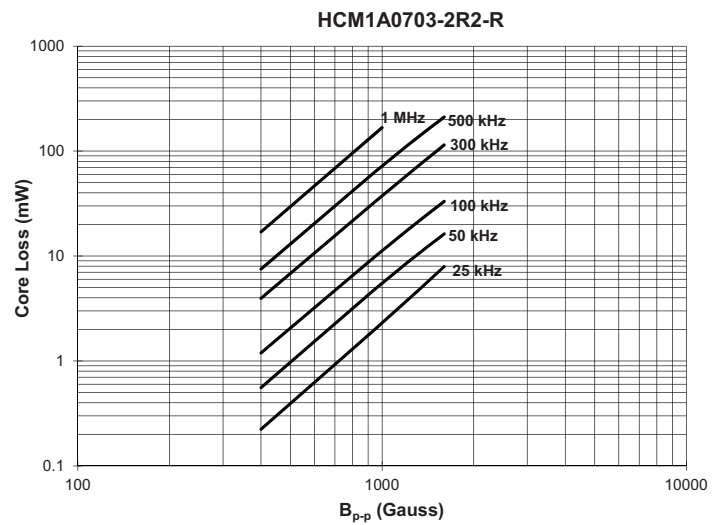
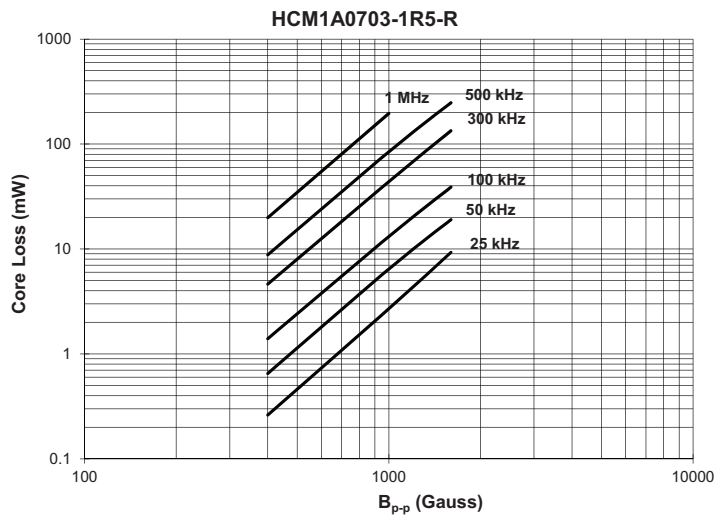
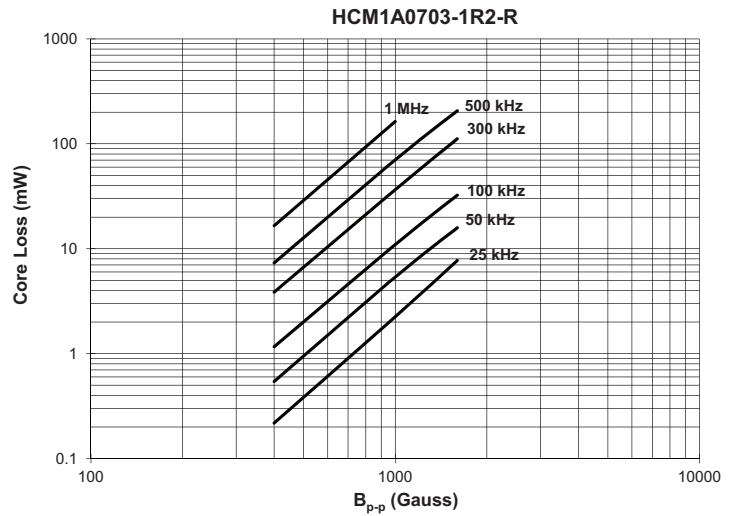
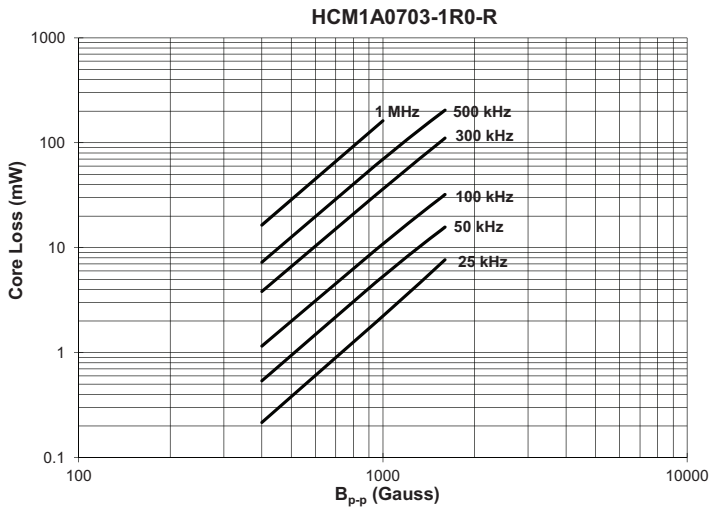
Core loss vs Bp-p



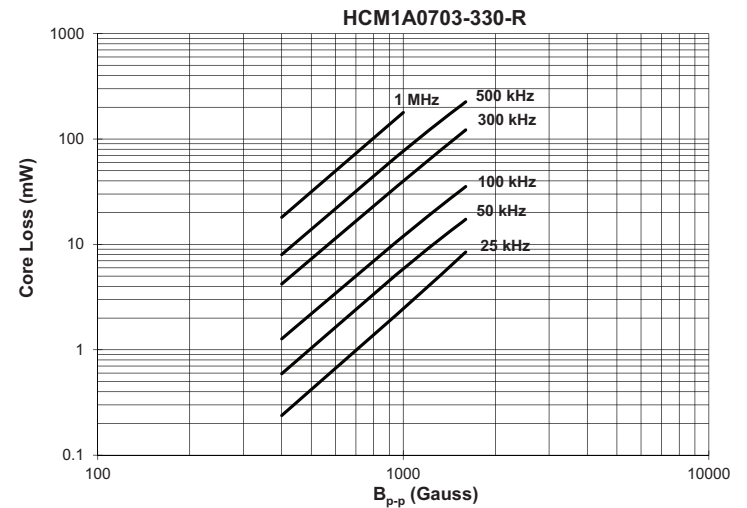
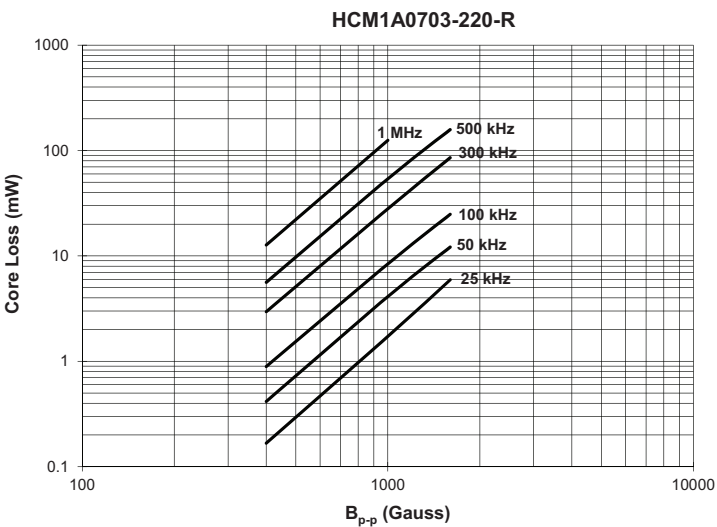
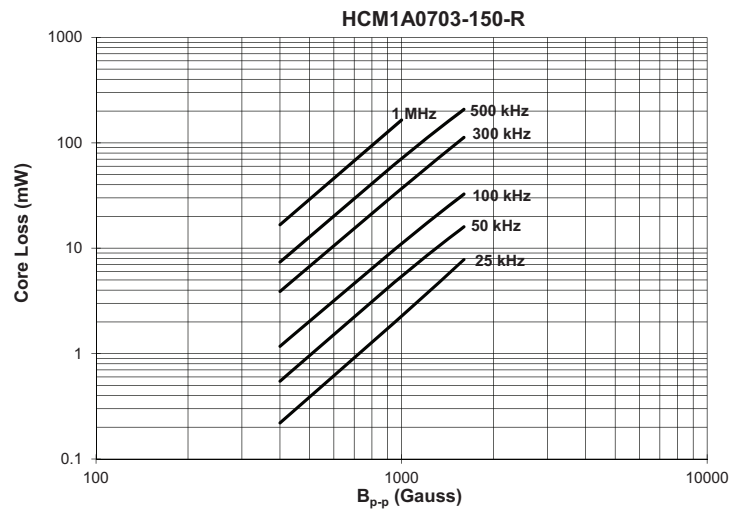
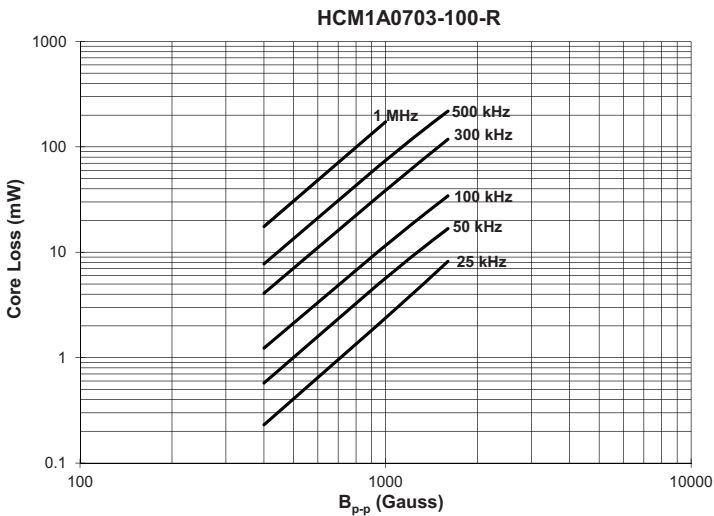
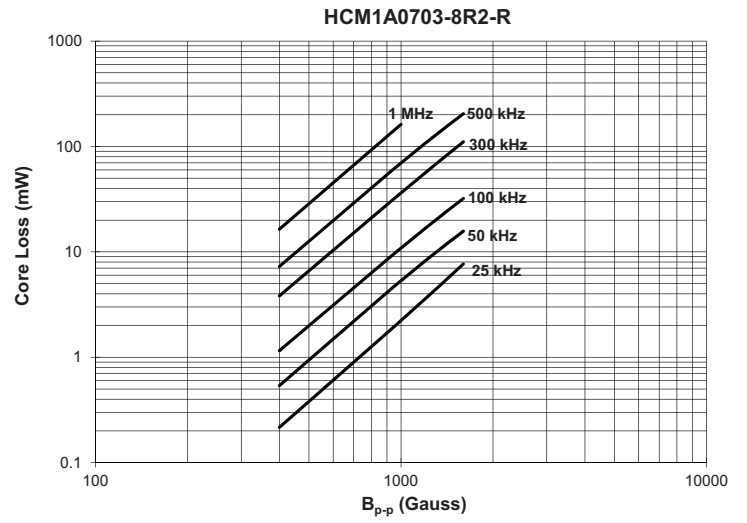
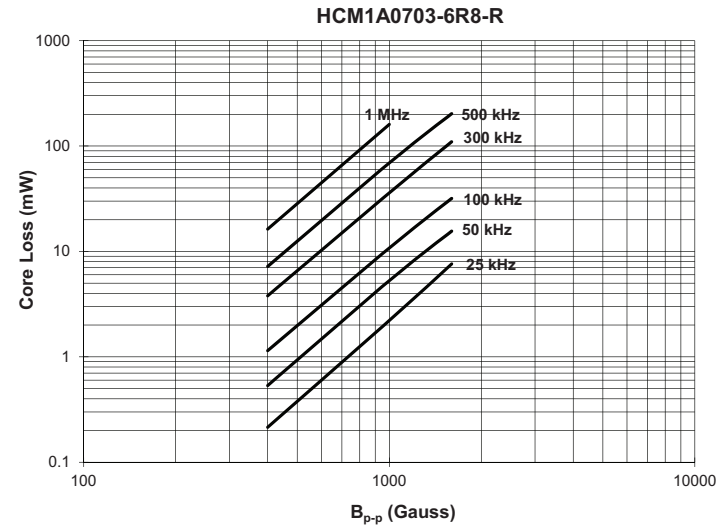
Core loss vs Bp-p



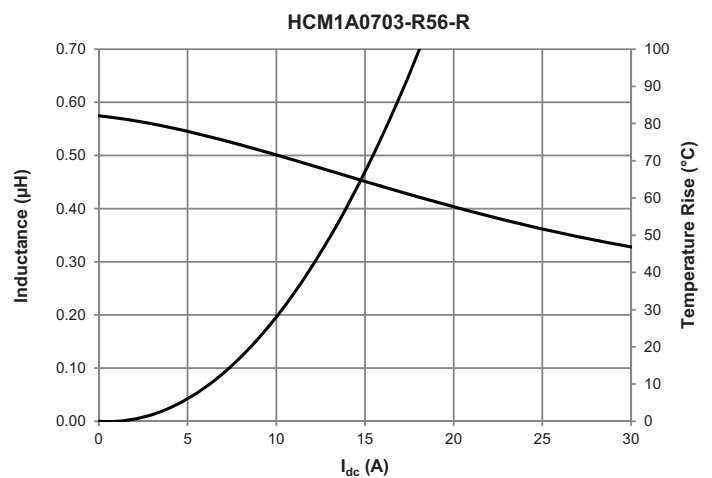
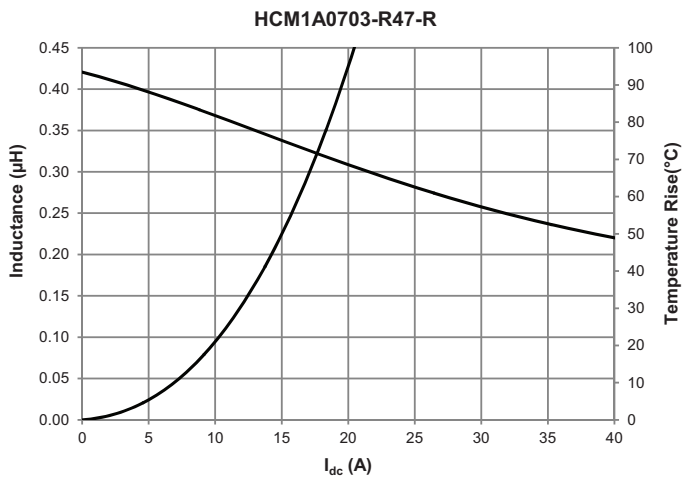
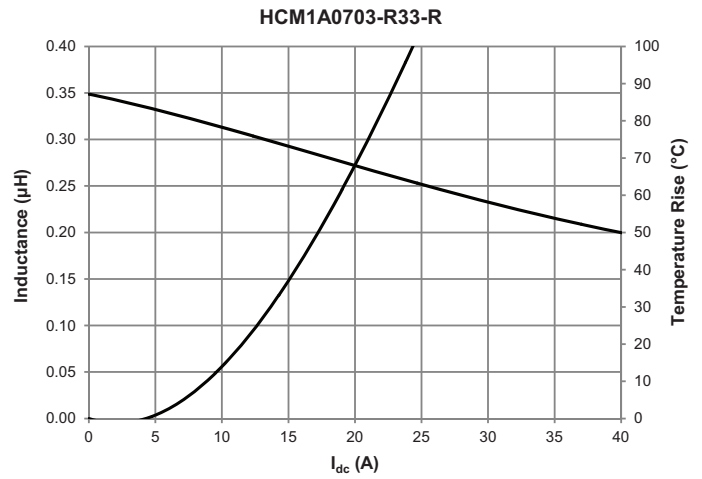
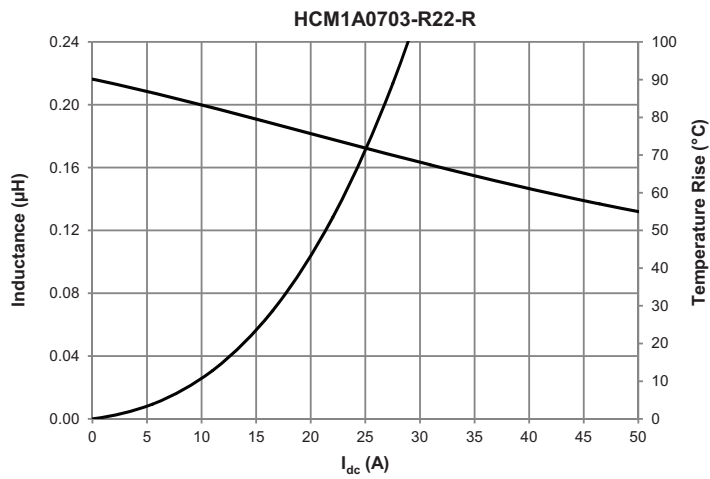
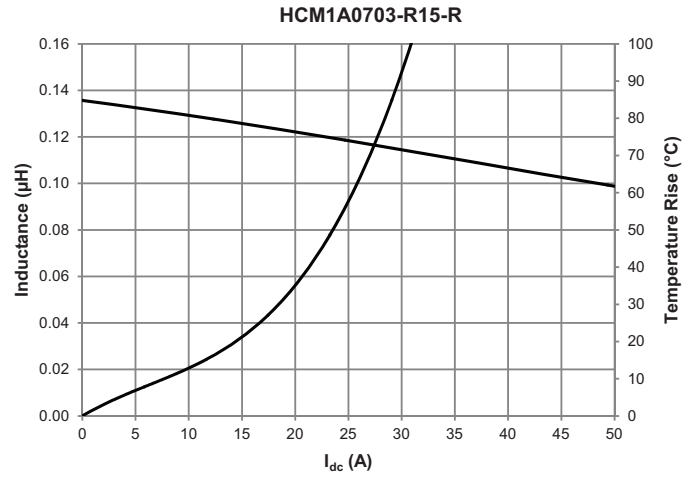
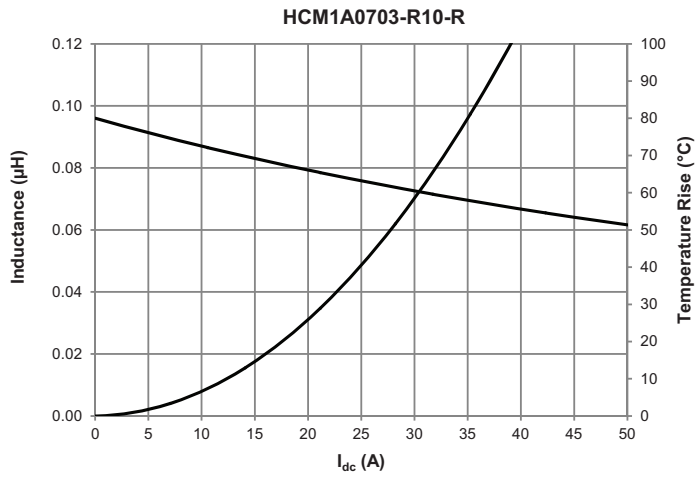
Core loss vs Bp-p



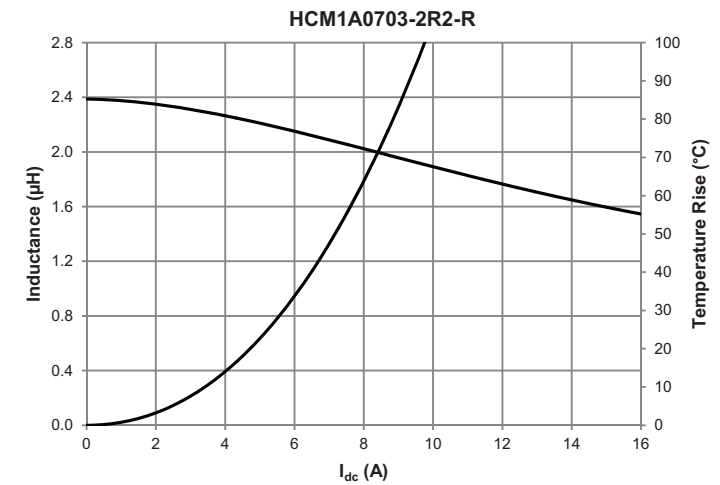
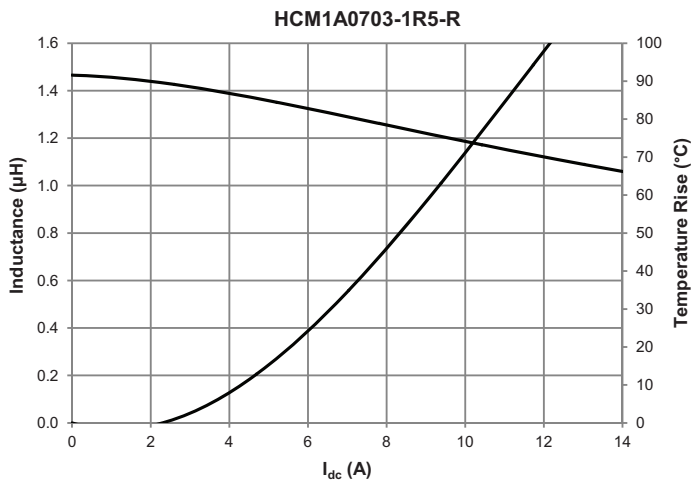
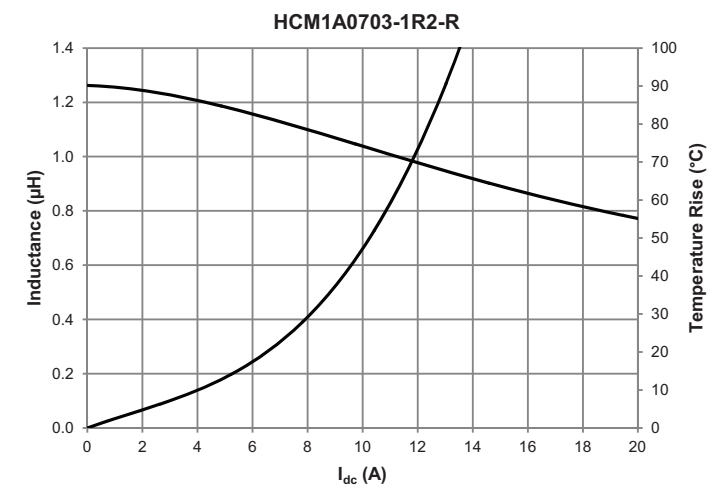
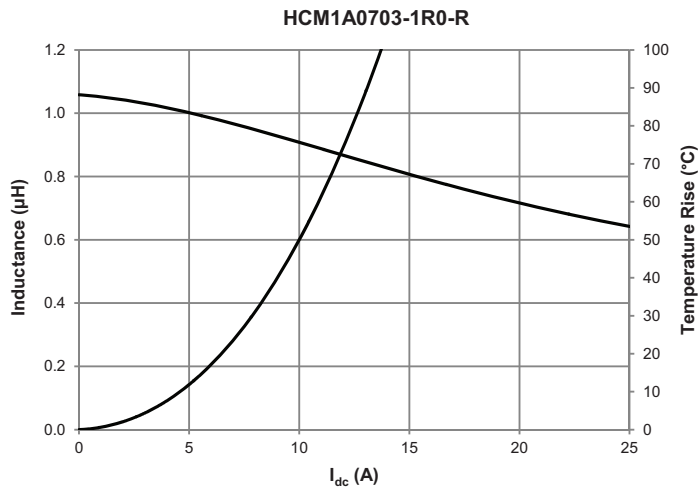
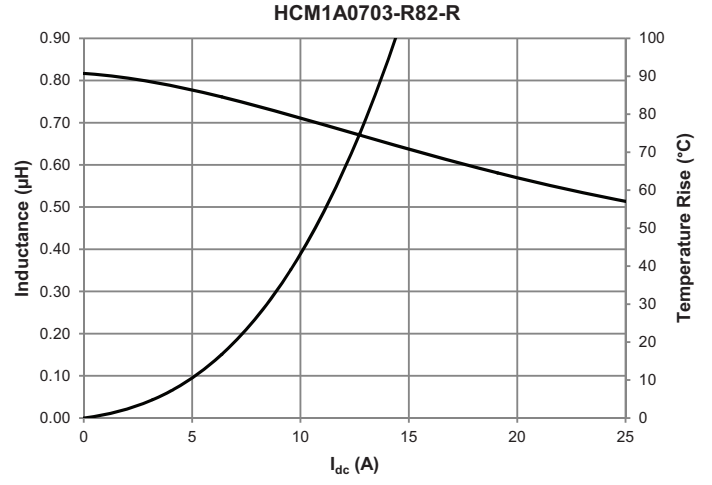
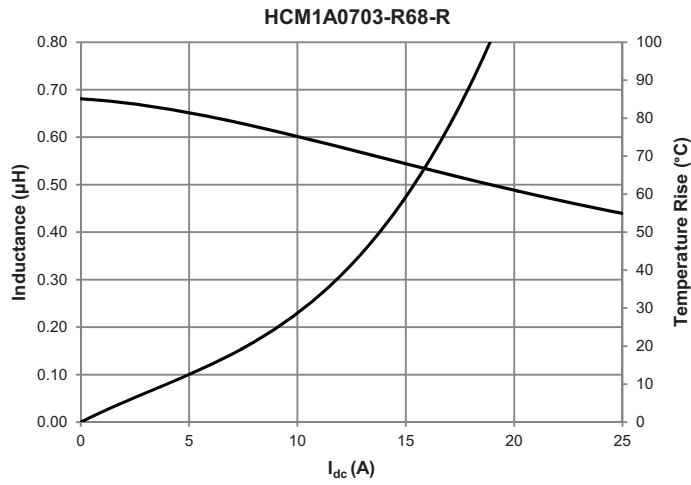
Core loss vs Bp-p



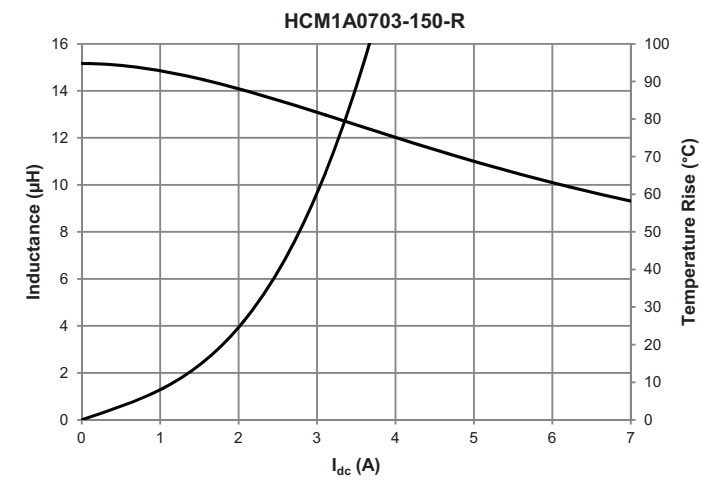
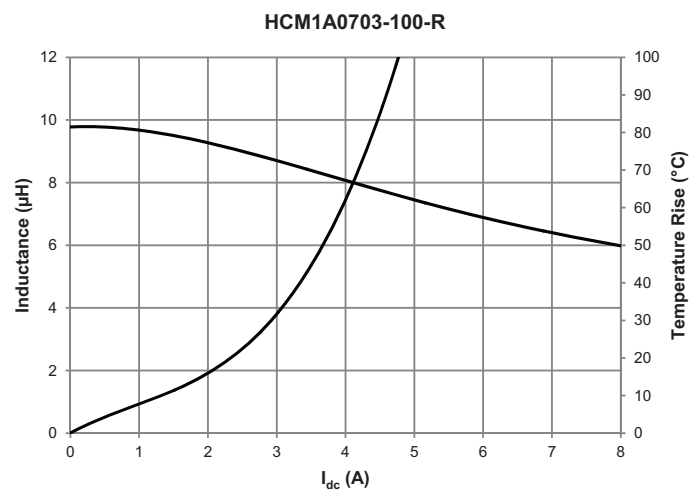
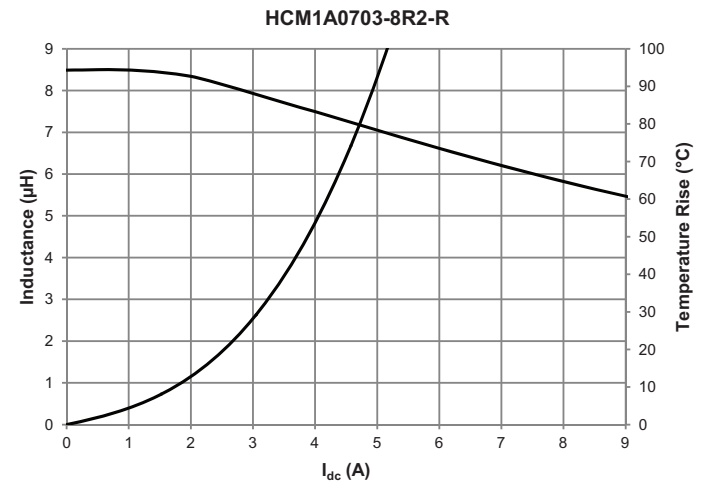
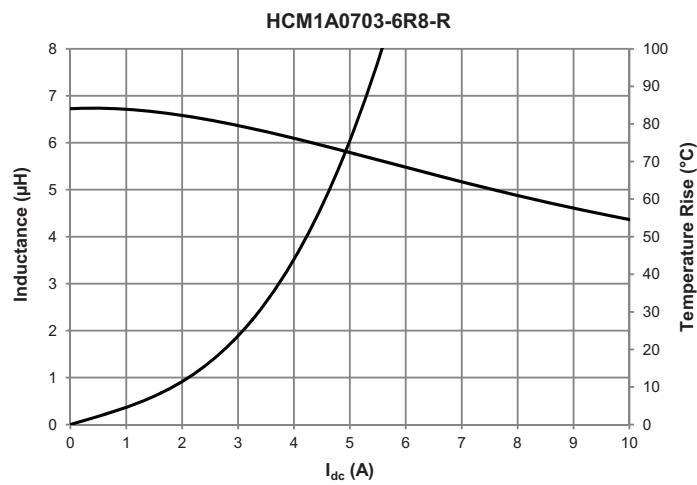
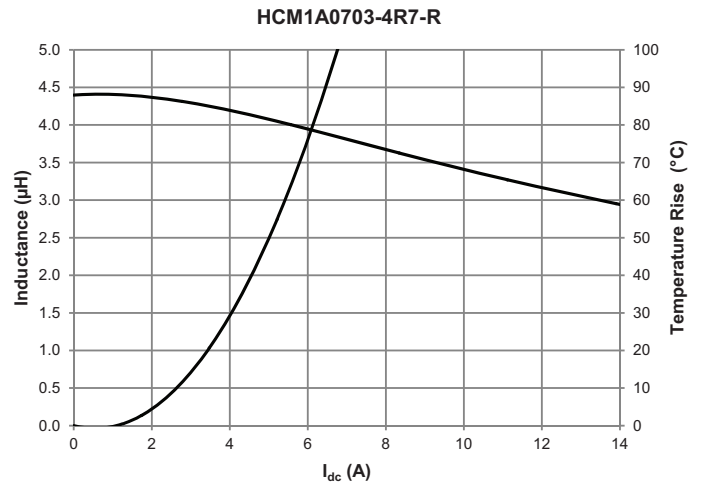
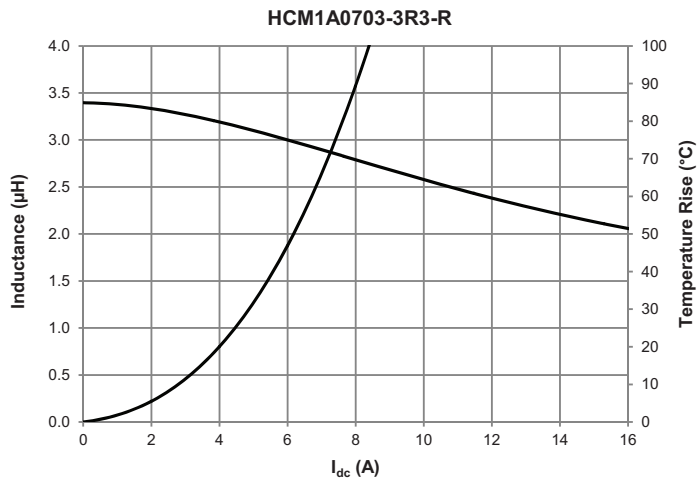
Inductance and temperature rise vs. current



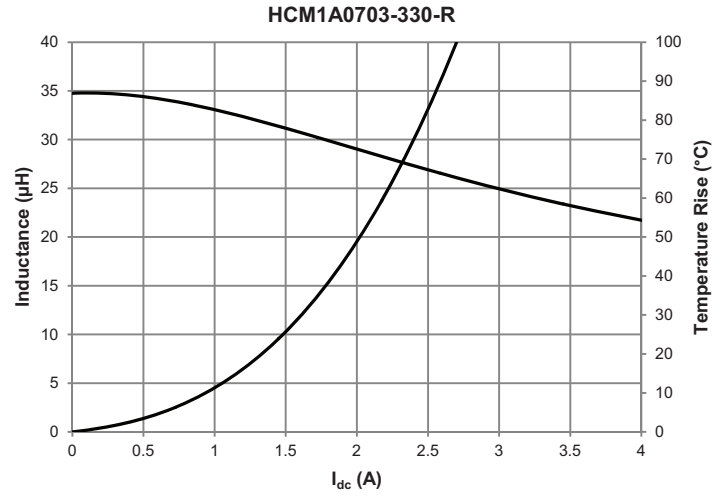
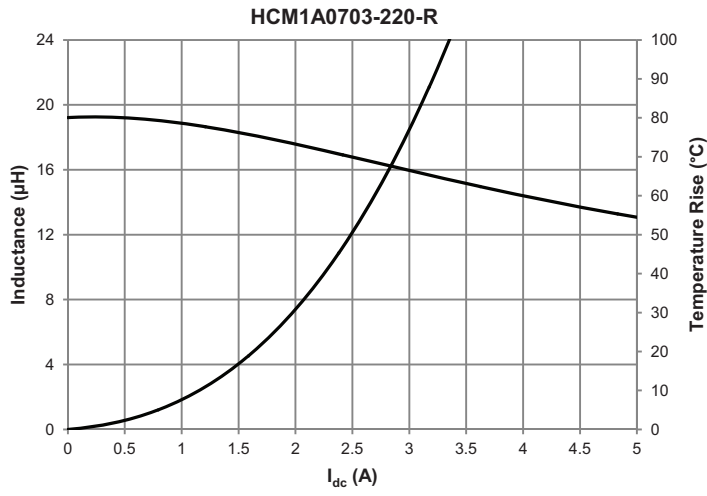
Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Inductance and temperature rise vs. current



Solder reflow profile

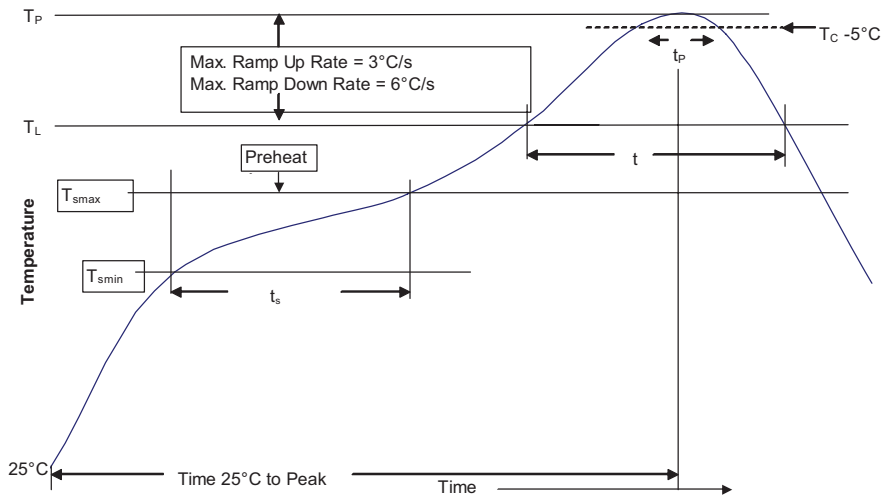


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
www.eaton.com/electronics

© 2016 Eaton
All Rights Reserved
Publication No. 10548 BU-MC16070
August 2016



Eaton is a registered trademark.
All other trademarks are property of their respective owners.